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Details	
Product Status	Active
Core Processor	12V1
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, IrDA, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3.13V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s12g128aclhr

Table 1-32. KGD Option for S12GA192 and S12GA240

	Function <----lowest-----PRIORITY-----highest---->				Power Supply	Internal Pull Resistor	
Wire Bond Die Pad	Pin	2nd Func.	3rd Func.	4th Func.		CTRL	Reset State
28	PB3	—	—	—	V_{DDX}	PUCR/PUPBE	Disabled
29	PP0	KWP0	ETRIG0	PWM0	V_{DDX}	PERP/PPSP	Disabled
30	PP1	KWP1	ETRIG1	PWM1	V_{DDX}	PERP/PPSP	Disabled
31	PP2	KWP2	ETRIG2	PWM2	V_{DDX}	PERP/PPSP	Disabled
32	PP3	KWP3	ETRIG3	PWM3	V_{DDX}	PERP/PPSP	Disabled
33	PP4	KWP4	PWM4	—	V_{DDX}	PERP/PPSP	Disabled
34	PP5	KWP5	PWM5	—	V_{DDX}	PERP/PPSP	Disabled
35	PP6	KWP6	PWM6	—	V_{DDX}	PERP/PPSP	Disabled
36	PP7	KWP7	PWM7	—	V_{DDX}	PERP/PPSP	Disabled
37	VDDX3	—	—	—	—	—	—
38	VSSX3	—	—	—	—	—	—
39	PT7	IOC7	—	—	V_{DDX}	PERT/PPST	Disabled
40	PT6	IOC6	—	—	V_{DDX}	PERT/PPST	Disabled
41	PT5	IOC5	—	—	V_{DDX}	PERT/PPST	Disabled
42	PT4	IOC4	—	—	V_{DDX}	PERT/PPST	Disabled
43	PT3	IOC3	—	—	V_{DDX}	PERT/PPST	Disabled
44	PT2	IOC2	—	—	V_{DDX}	PERT/PPST	Disabled
45	PT1	IOC1	—	—	V_{DDX}	PERT/PPST	Disabled
46	PT0	IOC0	—	—	V_{DDX}	PERT/PPST	Disabled
47	PB4	$\overline{\text{IRQ}}$	—	—	V_{DDX}	PUCR/PUPBE	Disabled
48	PB5	$\overline{\text{XIRQ}}$	—	—	V_{DDX}	PUCR/PUPBE	Disabled
49	PB6	—	—	—	V_{DDX}	PUCR/PUPBE	Disabled
50	PB7	—	—	—	V_{DDX}	PUCR/PUPBE	Disabled
51	PC0	—	—	—	V_{DDA}	PUCR/PUPCE	Disabled
52	PC1	—	—	—	V_{DDA}	PUCR/PUPCE	Disabled
53	PC2	—	—	—	V_{DDA}	PUCR/PUPCE	Disabled
54	PC3	—	—	—	V_{DDA}	PUCR/PUPCE	Disabled
55	PAD0	KWAD0	AN0	—	V_{DDA}	PER1AD/PPS1AD	Disabled
56	PAD8	KWAD8	AN8	—	V_{DDA}	PER0AD/PPS0AD	Disabled

2.4.3.7 Port C Data Direction Register (DDRC)

Address 0x0006 (G1) Access: User read/write[1]

	7	6	5	4	3	2	1	0
R W	DDRC7	DDRC6	DDRC5	DDRA4	DDRC3	DDRC2	DDRC1	DDRC0
Reset	0	0	0	0	0	0	0	0

Address 0x0006 (G2, G3) Access: User read only

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

Figure 2-8. Port C Data Direction Register (DDRC)

[1] Read: Anytime
Write: Anytime

Table 2-28. DDRC Register Field Descriptions

Field	Description
7-0 DDRC	**Port C Data Direction**— This bit determines whether the associated pin is an input or output. 1 Associated pin configured as output 0 Associated pin configured as input

2.4.3.8 Port D Data Direction Register (DDRD)

Address 0x0007 (G1) Access: User read/write[1]

	7	6	5	4	3	2	1	0
R W	DDRD7	DDRD6	DDRD5	DDRD4	DDRD3	DDRD2	DDRD1	DDRD0
Reset	0	0	0	0	0	0	0	0

Address 0x0007 (G2, G3) Access: User read only

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	0
W								
Reset	0	0	0	0	0	0	0	0

Figure 2-9. Port D Data Direction Register (DDRD)

[1] Read: Anytime
Write: Anytime

Table 8-32. Comparator C Access Considerations

Condition For Valid Match	Comp C Address	RWE	RW	Examples
Read and write accesses of ADDR[n]	ADDR[n][1]	0	X	LDAA ADDR[n] STAA #$BYTE ADDR[n]
Write accesses of ADDR[n]	ADDR[n]	1	0	STAA #$BYTE ADDR[n]
Read accesses of ADDR[n]	ADDR[n]	1	1	LDAA #$BYTE ADDR[n]

1 A word access of ADDR[n-1] also accesses ADDR[n] but does not generate a match. The comparator address register must contain the exact address from the code.

8.4.2.1.2 Comparator B

Comparator B offers address, direction (R/W) and access size (word/byte) comparison. If the SZE bit is set the access size (word or byte) is compared with the SZ bit value such that only the specified size of access causes a match. Thus if configured for a byte access of a particular address, a word access covering the same address does not lead to match.

Assuming the access direction is not qualified (RWE=0), for simplicity, the size access considerations are shown in Table 8-33.

Table 8-33. Comparator B Access Size Considerations

Condition For Valid Match	Comp B Address	RWE	SZE	SZ8	Examples
Word and byte accesses of ADDR[n]	ADDR[n][1]	0	0	X	MOVB #$BYTE ADDR[n] MOVW #$WORD ADDR[n]
Word accesses of ADDR[n] only	ADDR[n]	0	1	0	MOVW #$WORD ADDR[n] LDD ADDR[n]
Byte accesses of ADDR[n] only	ADDR[n]	0	1	1	MOVB #$BYTE ADDR[n] LDAB ADDR[n]

1 A word access of ADDR[n-1] also accesses ADDR[n] but does not generate a match. The comparator address register must contain the exact address from the code.

Access direction can also be used to qualify a match for Comparator B in the same way as described for Comparator C in Table 8-32.

8.4.2.1.3 Comparator A

Comparator A offers address, direction (R/W), access size (word/byte) and data bus comparison.

Table 8-34 lists access considerations with data bus comparison. On word accesses the data byte of the lower address is mapped to DBGADH. Access direction can also be used to qualify a match for Comparator A in the same way as described for Comparator C in Table 8-32.

Table 8-34. Comparator A Matches When Accessing ADDR[n]

SZE	SZ	DBGADHM, DBGADLM	Access DH=DBGADH, DL=DBGADL	Comment
0	X	$0000	Byte Word	No databus comparison

Table 10-3. CPMUFLG Field Descriptions (continued)

Field	Description
1 OSCIF	**Oscillator Interrupt Flag** — OSCIF is set to 1 when UPOSC status bit changes. This flag can only be cleared by writing a 1. Writing a 0 has no effect.If enabled (OSCIE=1), OSCIF causes an interrupt request. 0 No change in UPOSC bit. 1 UPOSC bit has changed.
0 UPOSC	**Oscillator Status Bit** — UPOSC reflects the status of the oscillator. Writes have no effect. While UPOSC=0 the OSCCLK going to the MSCAN module is off. Entering Full Stop Mode UPOSC is cleared. 0 The oscillator is off or oscillation is not qualified by the PLL. 1 The oscillator is qualified by the PLL.

10.3.2.5 S12CPMU Interrupt Enable Register (CPMUINT)

This register enables S12CPMU interrupt requests.

0x0038

	7	6	5	4	3	2	1	0
R	RTIE	0	0	LOCKIE	0	0	OSCIE	0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 10-8. S12CPMU Interrupt Enable Register (CPMUINT)

Read: Anytime

Write: Anytime

Table 10-4. CPMUINT Field Descriptions

Field	Description
7 RTIE	Real Time Interrupt Enable Bit 0 Interrupt requests from RTI are disabled. 1 Interrupt will be requested whenever RTIF is set.
4 LOCKIE	PLL Lock Interrupt Enable Bit 0 PLL LOCK interrupt requests are disabled. 1 Interrupt will be requested whenever LOCKIF is set.
1 OSCIE	Oscillator Corrupt Interrupt Enable Bit 0 Oscillator Corrupt interrupt requests are disabled. 1 Interrupt will be requested whenever OSCIF is set.

10.3.2.6 S12CPMU Clock Select Register (CPMUCLKS)

This register controls S12CPMU clock selection.

12.4 Functional Description

The ADC12B8C consists of an analog sub-block and a digital sub-block.

12.4.1 Analog Sub-Block

The analog sub-block contains all analog electronics required to perform a single conversion. Separate power supplies VDDA and VSSA allow to isolate noise of other MCU circuitry from the analog sub-block.

12.4.1.1 Sample and Hold Machine

The Sample and Hold Machine controls the storage and charge of the sample capacitor to the voltage level of the analog signal at the selected ADC input channel.

During the sample process the analog input connects directly to the storage node.

The input analog signals are unipolar and must be within the potential range of VSSA to VDDA.

During the hold process the analog input is disconnected from the storage node.

12.4.1.2 Analog Input Multiplexer

The analog input multiplexer connects one of the 8 external analog input channels to the sample and hold machine.

12.4.1.3 Analog-to-Digital (A/D) Machine

The A/D Machine performs analog to digital conversions. The resolution is program selectable to be either 8 or 10 or 12 bits. The A/D machine uses a successive approximation architecture. It functions by comparing the sampled and stored analog voltage with a series of binary coded discrete voltages.

By following a binary search algorithm, the A/D machine identifies the discrete voltage that is nearest to the sampled and stored voltage.

When not converting the A/D machine is automatically powered down.

Only analog input signals within the potential range of VRL to VRH (A/D reference potentials) will result in a non-railed digital output code.

12.4.2 Digital Sub-Block

This subsection describes some of the digital features in more detail. See Section 12.3.2, “Register Descriptions” for all details.

12.4.2.1 External Trigger Input

The external trigger feature allows the user to synchronize ATD conversions to an external event rather than relying only on software to trigger the ATD module when a conversion is about to take place. The external trigger signal (out of reset ATD channel 7, configurable in ATDCTL1) is programmable to be edge

Table 13-9. Examples of ideal decimal ATD Results

Input Signal VRL = 0 Volts VRH = 5.12 Volts	8-Bit Codes (resolution=20mV)	10-Bit Codes (resolution=5mV)	Reserved
5.120 Volts	255	1023	Reserved
...	...	...	
0.022	1	4	
0.020	1	4	
0.018	1	4	
0.016	1	3	
0.014	1	3	
0.012	1	2	
0.010	1	2	
0.008	0	2	
0.006	0	1	
0.004	0	1	
0.003	0	1	
0.002	0	0	
0.000	0	0	

Table 13-10. Conversion Sequence Length Coding

S8C	S4C	S2C	S1C	Number of Conversions per Sequence
0	0	0	0	12
0	0	0	1	1
0	0	1	0	2
0	0	1	1	3
0	1	0	0	4
0	1	0	1	5
0	1	1	0	6
0	1	1	1	7
1	0	0	0	8
1	0	0	1	9
1	0	1	0	10
1	0	1	1	11
1	1	0	0	12
1	1	0	1	12
1	1	1	0	12
1	1	1	1	12

Table 13-11. ATD Behavior in Freeze Mode (Breakpoint)

FRZ1	FRZ0	Behavior in Freeze Mode
0	0	Continue conversion

16.3.2.7 ATD Status Register 0 (ATDSTAT0)

This register contains the Sequence Complete Flag, overrun flags for external trigger and FIFO mode, and the conversion counter.

Module Base + 0x0006

	7	6	5	4	3	2	1	0
R	SCF	0	ETORF	FIFOR	CC3	CC2	CC1	CC0
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 16-9. ATD Status Register 0 (ATDSTAT0)

Read: Anytime

Write: Anytime (No effect on (CC3, CC2, CC1, CC0))

Table 16-16. ATDSTAT0 Field Descriptions

Field	Description
7 SCF	**Sequence Complete Flag** — This flag is set upon completion of a conversion sequence. If conversion sequences are continuously performed (SCAN=1), the flag is set after each one is completed. This flag is cleared when one of the following occurs: A) Write “1” to SCF B) Write to ATDCTL5 (a new conversion sequence is started) C) If AFFC=1 and a result register is read 0 Conversion sequence not completed 1 Conversion sequence has completed
5 ETORF	**External Trigger Overrun Flag** — While in edge sensitive mode (ETRIGLE=0), if additional active edges are detected while a conversion sequence is in process the overrun flag is set. This flag is cleared when one of the following occurs: A) Write “1” to ETORF B) Write to ATDCTL0,1,2,3,4, ATDCMPE or ATDCMPHT (a conversion sequence is aborted) C) Write to ATDCTL5 (a new conversion sequence is started) 0 No External trigger overrun error has occurred 1 External trigger overrun error has occurred
4 FIFOR	**Result Register Overrun Flag** — This bit indicates that a result register has been written to before its associated conversion complete flag (CCF) has been cleared. This flag is most useful when using the FIFO mode because the flag potentially indicates that result registers are out of sync with the input channels. However, it is also practical for non-FIFO modes, and indicates that a result register has been overwritten before it has been read (i.e. the old data has been lost). This flag is cleared when one of the following occurs: A) Write “1” to FIFOR B) Write to ATDCTL0,1,2,3,4, ATDCMPE or ATDCMPHT (a conversion sequence is aborted) C) Write to ATDCTL5 (a new conversion sequence is started) 0 No overrun has occurred 1 Overrun condition exists (result register has been written while associated CCFx flag was still set)

Module Base + 0x0006 Access: User read/write[1]

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	TXE2	TXE1	TXE0
W								
Reset:	0	0	0	0	0	1	1	1

= Unimplemented

Figure 18-10. MSCAN Transmitter Flag Register (CANTFLG)

[1] Read: Anytime
Write: Anytime when not in initialization mode; write of 1 clears flag, write of 0 is ignored

NOTE

The CANTFLG register is held in the reset state when the initialization mode is active (INITRQ = 1 and INITAK = 1). This register is writable when not in initialization mode (INITRQ = 0 and INITAK = 0).

Table 18-13. CANTFLG Register Field Descriptions

Field	Description
2-0 TXE[2:0]	**Transmitter Buffer Empty** — This flag indicates that the associated transmit message buffer is empty, and thus not scheduled for transmission. The CPU must clear the flag after a message is set up in the transmit buffer and is due for transmission. The MSCAN sets the flag after the message is sent successfully. The flag is also set by the MSCAN when the transmission request is successfully aborted due to a pending abort request (see Section 18.3.2.9, "MSCAN Transmitter Message Abort Request Register (CANTARQ)"). If not masked, a transmit interrupt is pending while this flag is set. Clearing a TXEx flag also clears the corresponding ABTAKx (see Section 18.3.2.10, "MSCAN Transmitter Message Abort Acknowledge Register (CANTAAK)"). When a TXEx flag is set, the corresponding ABTRQx bit is cleared (see Section 18.3.2.9, "MSCAN Transmitter Message Abort Request Register (CANTARQ)"). When listen-mode is active (see Section 18.3.2.2, "MSCAN Control Register 1 (CANCTL1)") the TXEx flags cannot be cleared and no transmission is started. Read and write accesses to the transmit buffer will be blocked, if the corresponding TXEx bit is cleared (TXEx = 0) and the buffer is scheduled for transmission. 0 The associated message buffer is full (loaded with a message due for transmission) 1 The associated message buffer is empty (not scheduled)

18.3.2.8 MSCAN Transmitter Interrupt Enable Register (CANTIER)

This register contains the interrupt enable bits for the transmit buffer empty interrupt flags.

If the WUPE bit in CANCTL0 is not asserted, the MSCAN will mask any activity it detects on CAN. RXCAN is therefore held internally in a recessive state. This locks the MSCAN in sleep mode. WUPE must be set before entering sleep mode to take effect.

The MSCAN is able to leave sleep mode (wake up) only when:

- CAN bus activity occurs and WUPE = 1

  or
- the CPU clears the SLPRQ bit

NOTE

The CPU cannot clear the SLPRQ bit before sleep mode (SLPRQ = 1 and SLPAK = 1) is active.

After wake-up, the MSCAN waits for 11 consecutive recessive bits to synchronize to the CAN bus. As a consequence, if the MSCAN is woken-up by a CAN frame, this frame is not received.

The receive message buffers (RxFG and RxBG) contain messages if they were received before sleep mode was entered. All pending actions will be executed upon wake-up; copying of RxBG into RxFG, message aborts and message transmissions. If the MSCAN remains in bus-off state after sleep mode was exited, it continues counting the 128 occurrences of 11 consecutive recessive bits.

18.4.5.6 MSCAN Power Down Mode

The MSCAN is in power down mode (Table 18-38) when

- CPU is in stop mode

  or
- CPU is in wait mode and the CSWAI bit is set

When entering the power down mode, the MSCAN immediately stops all ongoing transmissions and receptions, potentially causing CAN protocol violations. To protect the CAN bus system from fatal consequences of violations to the above rule, the MSCAN immediately drives TXCAN into a recessive state.

NOTE

The user is responsible for ensuring that the MSCAN is not active when power down mode is entered. The recommended procedure is to bring the MSCAN into Sleep mode before the STOP or WAI instruction (if CSWAI is set) is executed. Otherwise, the abort of an ongoing message can cause an error condition and impact other CAN bus devices.

In power down mode, all clocks are stopped and no registers can be accessed. If the MSCAN was not in sleep mode before power down mode became active, the module performs an internal recovery cycle after powering up. This causes some fixed delay before the module enters normal mode again.

20.1.4 Block Diagram

Figure 20-1 is a high level block diagram of the SCI module, showing the interaction of various function blocks.

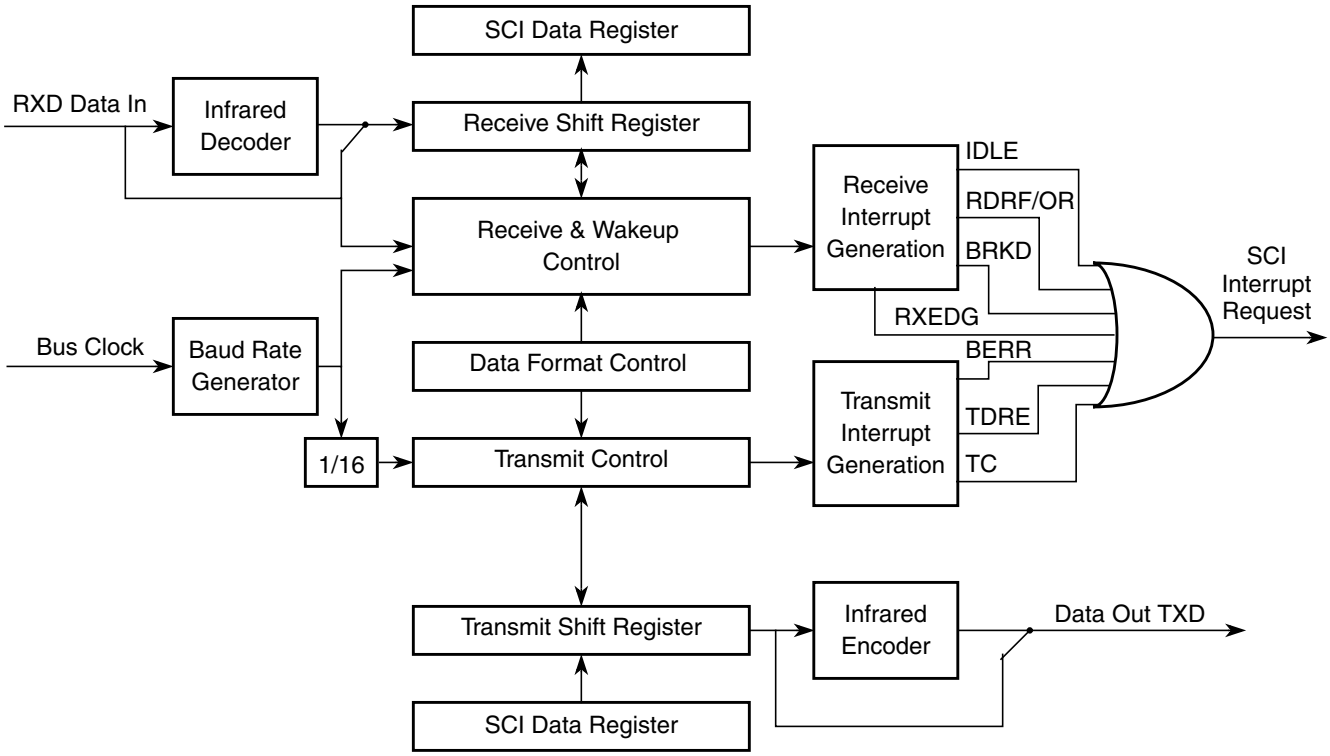

Figure 20-1. SCI Block Diagram

20.2 External Signal Description

The SCI module has a total of two external pins.

20.2.1 TXD — Transmit Pin

The TXD pin transmits SCI (standard or infrared) data. It will idle high in either mode and is high impedance anytime the transmitter is disabled.

20.2.2 RXD — Receive Pin

The RXD pin receives SCI (standard or infrared) data. An idle line is detected as a line high. This input is ignored when the receiver is disabled and should be terminated to a known voltage.

20.3 Memory Map and Register Definition

This section provides a detailed description of all the SCI registers.

Table 20-9. Bit Error Mode Coding

BERRM1	BERRM0	Function
1	1	Reserved

20.3.2.6 SCI Control Register 2 (SCICR2)

Module Base + 0x0003

	7	6	5	4	3	2	1	0
R W	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
Reset	0	0	0	0	0	0	0	0

Figure 20-9. SCI Control Register 2 (SCICR2)

Read: Anytime

Write: Anytime

Table 20-10. SCICR2 Field Descriptions

Field	Description
7 TIE	**Transmitter Interrupt Enable Bit** — TIE enables the transmit data register empty flag, TDRE, to generate interrupt requests. 0 TDRE interrupt requests disabled 1 TDRE interrupt requests enabled
6 TCIE	**Transmission Complete Interrupt Enable Bit** — TCIE enables the transmission complete flag, TC, to generate interrupt requests. 0 TC interrupt requests disabled 1 TC interrupt requests enabled
5 RIE	**Receiver Full Interrupt Enable Bit** — RIE enables the receive data register full flag, RDRF, or the overrun flag, OR, to generate interrupt requests. 0 RDRF and OR interrupt requests disabled 1 RDRF and OR interrupt requests enabled
4 ILIE	**Idle Line Interrupt Enable Bit** — ILIE enables the idle line flag, IDLE, to generate interrupt requests. 0 IDLE interrupt requests disabled 1 IDLE interrupt requests enabled
3 TE	**Transmitter Enable Bit** — TE enables the SCI transmitter and configures the TXD pin as being controlled by the SCI. The TE bit can be used to queue an idle preamble. 0 Transmitter disabled 1 Transmitter enabled
2 RE	**Receiver Enable Bit** — RE enables the SCI receiver. 0 Receiver disabled 1 Receiver enabled

20.4.4 Baud Rate Generation

A 13-bit modulus counter in the baud rate generator derives the baud rate for both the receiver and the transmitter. The value from 0 to 8191 written to the SBR12:SBR0 bits determines the bus clock divisor. The SBR bits are in the SCI baud rate registers (SCIBDH and SCIBDL). The baud rate clock is synchronized with the bus clock and drives the receiver. The baud rate clock divided by 16 drives the transmitter. The receiver has an acquisition rate of 16 samples per bit time.

Baud rate generation is subject to one source of error:

- Integer division of the bus clock may not give the exact target frequency.

Table 20-16 lists some examples of achieving target baud rates with a bus clock frequency of 25 MHz.

When IREN = 0 then,

SCI baud rate = SCI bus clock / (16 * SCIBR[12:0])

Table 20-16. Baud Rates (Example: Bus Clock = 25 MHz)

Bits SBR[12:0]	Receiver Clock (Hz)	Transmitter Clock (Hz)	Target Baud Rate	Error (%)
41	609,756.1	38,109.8	38,400	.76
81	308,642.0	19,290.1	19,200	.47
163	153,374.2	9585.9	9,600	.16
326	76,687.1	4792.9	4,800	.15
651	38,402.5	2400.2	2,400	.01
1302	19,201.2	1200.1	1,200	.01
2604	9600.6	600.0	600	.00
5208	4800.0	300.0	300	.00

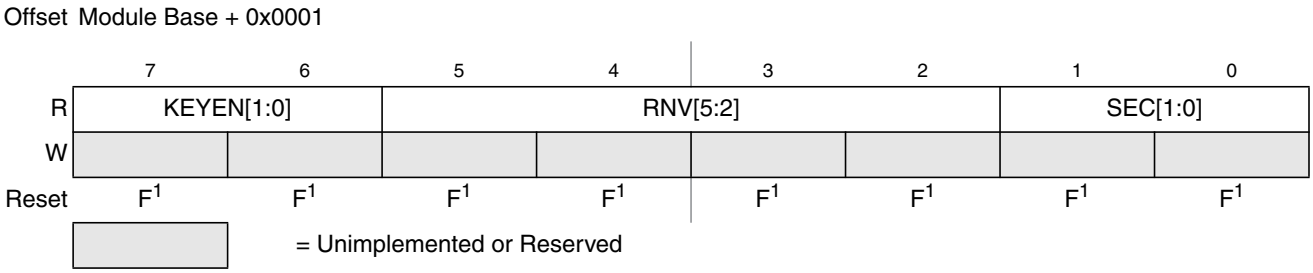

Figure 24-6. Flash Security Register (FSEC)

1 Loaded from IFR Flash configuration field, during reset sequence.

All bits in the FSEC register are readable but not writable.

During the reset sequence, the FSEC register is loaded with the contents of the Flash security byte in the Flash configuration field at global address 0x3_FF0F located in P-Flash memory (see Table 24-4) as indicated by reset condition F in Figure 24-6. If a double bit fault is detected while reading the P-Flash phrase containing the Flash security byte during the reset sequence, all bits in the FSEC register will be set to leave the Flash module in a secured state with backdoor key access disabled.

Table 24-9. FSEC Field Descriptions

Field	Description
7–6 KEYEN[1:0]	**Backdoor Key Security Enable Bits** — The KEYEN[1:0] bits define the enabling of backdoor key access to the Flash module as shown in Table 24-10.
5–2 RNV[5:2]	**Reserved Nonvolatile Bits** — The RNV bits should remain in the erased state for future enhancements.
1–0 SEC[1:0]	**Flash Security Bits** — The SEC[1:0] bits define the security state of the MCU as shown in Table 24-11. If the Flash module is unsecured using backdoor key access, the SEC bits are forced to 10.

Table 24-10. Flash KEYEN States

KEYEN[1:0]	Status of Backdoor Key Access
00	DISABLED
01	DISABLED[1]
10	ENABLED
11	DISABLED

1 Preferred KEYEN state to disable backdoor key access.

Table 24-11. Flash Security States

SEC[1:0]	Status of Security
00	SECURED
01	SECURED[1]
10	UNSECURED
11	SECURED

1 Preferred SEC state to set MCU to secured state.

Upon clearing CCIF to launch the Set User Margin Level command, the Memory Controller will set the user margin level for the targeted block and then set the CCIF flag.

NOTE

When the EEPROM block is targeted, the EEPROM user margin levels are applied only to the EEPROM reads. However, when the P-Flash block is targeted, the P-Flash user margin levels are applied to both P-Flash and EEPROM reads. It is not possible to apply user margin levels to the P-Flash block only.

Valid margin level settings for the Set User Margin Level command are defined in Table 25-55.

Table 25-55. Valid Set User Margin Level Settings

CCOB (CCOBIX=001)	Level Description
0x0000	Return to Normal Level
0x0001	User Margin-1 Level[1]
0x0002	User Margin-0 Level[2]

[1] Read margin to the erased state

[2] Read margin to the programmed state

Table 25-56. Set User Margin Level Command Error Handling

Register	Error Bit	Error Condition
FSTAT	ACCERR	Set if CCOBIX[2:0] != 001 at command launch
		Set if command not available in current mode (see Table 25-27)
		Set if an invalid FlashBlockSelectionCode[1:0] is supplied (See Table 25-34)
		Set if an invalid margin level setting is supplied
	FPVIOL	None
	MGSTAT1	None
	MGSTAT0	None

NOTE

User margin levels can be used to check that Flash memory contents have adequate margin for normal level read operations. If unexpected results are encountered when checking Flash memory contents at user margin levels, a potential loss of information has been detected.

Table 27-6. Memory Controller Resource Fields (NVMRES[1]=1)

Global Address	Size (Bytes)	Description
0x0_4000 – 0x040FF	256	P-Flash IFR (see Table 27-5)
0x0_4100 – 0x0_41FF	256	Reserved.
0x0_4200 – 0x0_57FF		Reserved
0x0_5800 – 0x0_59FF	512	Reserved
0x0_5A00 – 0x0_5FFF	1,536	Reserved
0x0_6000 – 0x0_6BFF	3,072	Reserved
0x0_6C00 – 0x0_7FFF	5,120	Reserved

1 NVMRES - See Section 27.4.3 for NVMRES (NVM Resource) detail.

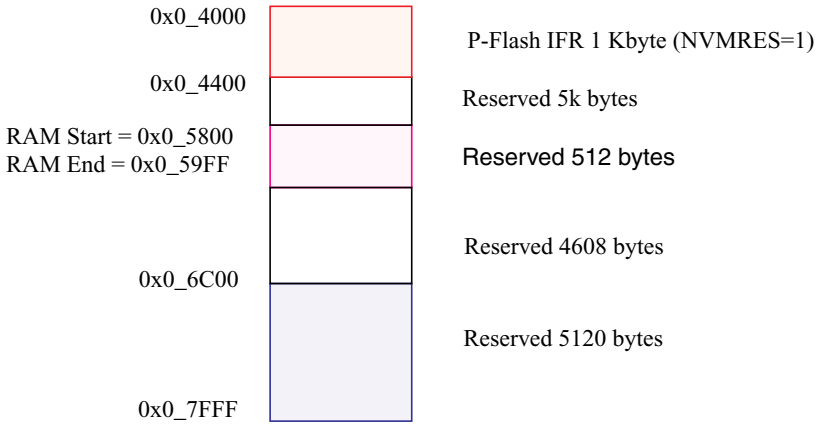

Figure 27-3. Memory Controller Resource Memory Map (NVMRES=1)

27.3.2 Register Descriptions

The Flash module contains a set of 20 control and status registers located between Flash module base + 0x0000 and 0x0013.

In the case of the writable registers, the write accesses are forbidden during Fash command execution (for more detail, see Caution note in Section 27.3).

Table 27-41. Program P-Flash Command Error Handling

Register	Error Bit	Error Condition
FSTAT	ACCERR	Set if CCOBIX[2:0] != 101 at command launch
		Set if command not available in current mode (see Table 27-27)
		Set if an invalid global address [17:0] is supplied see Table 27-3)
		Set if a misaligned phrase address is supplied (global address [2:0] != 000)
	FPVIOL	Set if the global address [17:0] points to a protected area
	MGSTAT1	Set if any errors have been encountered during the verify operation
	MGSTAT0	Set if any non-correctable errors have been encountered during the verify operation

27.4.6.6 Program Once Command

The Program Once command restricts programming to a reserved 64 byte field (8 phrases) in the nonvolatile information register located in P-Flash. The Program Once reserved field can be read using the Read Once command as described in Section 27.4.6.4. The Program Once command must only be issued once since the nonvolatile information register in P-Flash cannot be erased. The Program Once command must not be executed from the Flash block containing the Program Once reserved field to avoid code runaway.

Table 27-42. Program Once Command FCCOB Requirements

CCOBIX[2:0]	FCCOB Parameters	
000	0x07	Not Required
001	Program Once phrase index (0x0000 - 0x0007)	
010	Program Once word 0 value	
011	Program Once word 1 value	
100	Program Once word 2 value	
101	Program Once word 3 value	

Upon clearing CCIF to launch the Program Once command, the Memory Controller first verifies that the selected phrase is erased. If erased, then the selected phrase will be programmed and then verified with read back. The CCIF flag will remain clear, setting only after the Program Once operation has completed.

The reserved nonvolatile information register accessed by the Program Once command cannot be erased and any attempt to program one of these phrases a second time will not be allowed. Valid phrase index values for the Program Once command range from 0x0000 to 0x0007. During execution of the Program Once command, any attempt to read addresses within P-Flash will return invalid data.

Table 31-13. FCNFG Field Descriptions

Field	Description
7 CCIE	**Command Complete Interrupt Enable** — The CCIE bit controls interrupt generation when a Flash command has completed. 0 Command complete interrupt disabled 1 An interrupt will be requested whenever the CCIF flag in the FSTAT register is set (see Section 31.3.2.7)
4 IGNSF	**Ignore Single Bit Fault** — The IGNSF controls single bit fault reporting in the FERSTAT register (see Section 31.3.2.8). 0 All single bit faults detected during array reads are reported 1 Single bit faults detected during array reads are not reported and the single bit fault interrupt will not be generated
1 FDFD	**Force Double Bit Fault Detect** — The FDFD bit allows the user to simulate a double bit fault during Flash array read operations and check the associated interrupt routine. The FDFD bit is cleared by writing a 0 to FDFD. 0 Flash array read operations will set the DFDIF flag in the FERSTAT register only if a double bit fault is detected 1 Any Flash array read operation will force the DFDIF flag in the FERSTAT register to be set (see Section 31.3.2.7) and an interrupt will be generated as long as the DFDIE interrupt enable in the FERCNFG register is set (see Section 31.3.2.6)
0 FSFD	**Force Single Bit Fault Detect** — The FSFD bit allows the user to simulate a single bit fault during Flash array read operations and check the associated interrupt routine. The FSFD bit is cleared by writing a 0 to FSFD. 0 Flash array read operations will set the SFDIF flag in the FERSTAT register only if a single bit fault is detected 1 Flash array read operation will force the SFDIF flag in the FERSTAT register to be set (see Section 31.3.2.7) and an interrupt will be generated as long as the SFDIE interrupt enable in the FERCNFG register is set (see Section 31.3.2.6)

31.3.2.6 Flash Error Configuration Register (FERCNFG)

The FERCNFG register enables the Flash error interrupts for the FERSTAT flags.

Offset Module Base + 0x0005

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	DFDIE	SFDIE
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 31-10. Flash Error Configuration Register (FERCNFG)

All assigned bits in the FERCNFG register are readable and writable.

Table A-5. Thermal Package Characteristics[1]

Num	C	Rating	Symbol	S12GN32, S12GNA32, S12GN16, S12GNA16	S12G64, S12GA64, S12G48, S12GN48, S12GA64	S12G128, S12GA128, S12G96, S12GA96	S12G240, S12GA240, S12G192, S12GA192	Unit
20-pin TSSOP								
1	D	Thermal resistance single sided PCB, natural convection[2]	θ_{JA}	91				°C/W
2	D	Thermal resistance single sided PCB @ 200 ft/min[3]	θ_{JMA}	72				°C/W
3	D	Thermal resistance double sided PCB with 2 internal planes, natural convection[3]	θ_{JA}	58				°C/W
4	D	Thermal resistance double sided PCB with 2 internal planes @ 200 ft/min[3]	θ_{JMA}	51				°C/W
5	D	Junction to Board[4]	θ_{JB}	29				°C/W
6	D	Junction to Case[5]	θ_{JC}	20				°C/W
7	D	Junction to Package Top[6]	Ψ_{JT}	4				°C/W
32-pin LQFP								
8	D	Thermal resistance single sided PCB, natural convection[2]	θ_{JA}	81	84			°C/W
9	D	Thermal resistance single sided PCB @ 200 ft/min[3]	θ_{JMA}	68	70			°C/W
10	D	Thermal resistance double sided PCB with 2 internal planes, natural convection[3]	θ_{JA}	57	56			°C/W
11	D	Thermal resistance double sided PCB with 2 internal planes @ 200 ft/min[3]	θ_{JMA}	50	49			°C/W
12	D	Junction to Board[4]	θ_{JB}	35	32			°C/W
13	D	Junction to Case[5]	θ_{JC}	25	23			°C/W
14	D	Junction to Package Top[6]	Ψ_{JT}	8	6			°C/W
48-pin LQFP								
15	D	Thermal resistance single sided PCB, natural convection[2]	θ_{JA}	81	80	79	75	°C/W
16	D	Thermal resistance single sided PCB @ 200 ft/min[3]	θ_{JMA}	68	67	66	62	°C/W
17	D	Thermal resistance double sided PCB with 2 internal planes, natural convection[3]	θ_{JA}	57	56	56	51	°C/W
18	D	Thermal resistance double sided PCB with 2 internal planes @ 200 ft/min[3]	θ_{JMA}	50	50	49	45	°C/W
19	D	Junction to Board[4]	θ_{JB}	35	34	33	30	°C/W
20	D	Junction to Case[5]	θ_{JC}	25	24	21	19	°C/W
21	D	Junction to Package Top[6]	Ψ_{JT}	8	6	4	N/A	°C/W

A.8.2 Electrical Characteristics for the PLL

Table A-40. PLL Characteristics

Conditions are shown in Table A-15 unless otherwise noted							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	D	VCO frequency during system reset	f_{VCORST}	8		25	MHz
2	C	VCO locking range	f_{VCO}	32		50	MHz
3	C	Reference Clock	f_{REF}	1			MHz
4	D	Lock Detection	$\lvert\Delta_{Lock}\rvert$	0		1.5	%[1]
5	D	Un-Lock Detection	$\lvert\Delta_{unl}\rvert$	0.5		2.5	%[1]
6	C	Time to lock	t_{lock}			150 + $256/f_{REF}$	µs
7	C	Jitter fit parameter 1[2] IRC as reference clock source	j_{irc}			1.4	%
8	C	Jitter fit parameter 1[3] XOSCLCP as reference clock source	j_{ext}			1.0	%

1 % deviation from target frequency

2 f_{REF} = 1MHz (IRC), f_{BUS} = 25MHz equivalent f_{PLL} = 50MHz, CPMUSYNR=0x58, CPMUREFDIV=0x00, CPMUPOSTDIV=0x00

3 f_{REF} = 4MHz (XOSCLCP), f_{BUS} = 24MHz equivalent f_{PLL} = 48MHz, CPMUSYNR=0x05, CPMUREFDIV=0x40, CPMUPOSTDIV=0x00

A.9 Electrical Characteristics for the IRC1M

Table A-41. IRC1M Characteristics (Junction Temperature From –40°C To +150°C, all packages)

Conditions are: Temperature option C, V, or M (see Table A-4)							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	P	Internal Reference Frequency, factory trimmed	f_{IRC1M_TRIM}	0.987	1	1.013	MHz

Table A-42. IRC1M Characteristics (Junction Temperature From –40°C To +150°C, KGD)

Conditions are: Temperature option C, V, or M (see Table A-4)							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	P	Internal Reference Frequency, factory trimmed	f_{IRC1M_TRIM}	0.980	1	1.020	MHz